

SOT-227 Single Thyristor Power Module, 160 A, 1200 V



| PRIMARY CHARACTERISTICS | | | | | |
|---|----------------------|--|--|--|--|
| V _{RRM} / V _{DRM} | 1200 V | | | | |
| V _{TM} (typical) at 150 A, 25 °C | 1.3 V | | | | |
| I _{T(AV)} , T _C = 75 °C | 158 A ⁽¹⁾ | | | | |
| Package | SOT-227 | | | | |
| Circuit | Single thyristor | | | | |

Note

FEATURES

- High voltage
- Industrial standard package
- Low thermal resistance
- UL pending
- · Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

BENEFITS

- Excellent thermal performances
- · High surge capability
- · Easy mounting on heatsink
- Thyristor for line frequency

APPLICATIONS

Line rectifying 50 Hz / 60 Hz

- · Softstart AC motor control
- DC motor control
- Power converter
- AC power control
- · Lighting and temperature control

| MAJOR RATINGS AND CHARACTERISTICS | | | | | |
|-------------------------------------|-----------------|-------------|-------------------|--|--|
| SYMBOL | CHARACTERISTICS | VALUES | UNITS | | |
| I _{T(AV)} | 75 °C | 158 | | | |
| ı | 50 Hz | 1390 | А | | |
| ITSM | 60 Hz | 1455 | | | |
| l ² t | 50 Hz | 9.6 | kA ² s | | |
| 1-1 | 60 Hz | 8.8 | KA-S | | |
| I ² √t | | 96.6 | kA²√s | | |
| V _{RRM} / V _{DRM} | | 1200 | V | | |
| T _{Stg} | | -40 to +125 | °C | | |
| TJ | | -40 to +125 | | | |

ELECTRICAL SPECIFICATIONS

| VOLTAGE RATINGS | | | | | | | |
|-----------------|--|--|---|---|--|--|--|
| | V _{RRM} , MUM REPETITIVE PEAK EVERSE VOLTAGE V | V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V | V _{DRM} , MAXIMUM REPETITIVE PEAK OFF-STATE VOLTAGE, GATE OPEN CIRCUIT V | I _{RRM,} I _{DRM} AT 125 °C mA | | | |
| | 1200 | 1300 | 1200 | 10 | | | |

⁽¹⁾ Maximum continuous collector current admitted 100 A to do not exceed the maximum temperature of terminals



www.vishay.com Vishay Semiconductors

| PARAMETER | SYMBOL | TEST CONDITIONS | | VALUES | UNITS | |
|---|------------------------|--|---|-----------------------------|-------|-------------------|
| Maximum average on-state current (thyristors) | I _{T(AV)} | 180° conduction, half sine wave, T _C = 75 °C | | 158 | | |
| Maximum peak, one-cycle non-repetitive | | t = 10 ms | No voltage | Sinusoidal half wave, | 1390 | |
| | | t = 8.3 ms | reapplied | | 1455 | А |
| on-state | I _{TSM} | t = 10 ms | | initial | 1169 | |
| | | t = 8.3 ms | reapplied | $T_J = T_J \text{ maximum}$ | 1224 | |
| | | t = 10 ms | No voltage | | 9.6 | |
| Maximum I ² t for fusing | l ² t | t = 8.3 ms | reapplied | Initial | 8.8 | kA ² s |
| Maximum 12t for fusing | 1-1 | t = 10 ms | 100 % V _{RRM} | $T_J = T_J \text{ maximum}$ | 6.8 | |
| | t = 8.3 ms reapplied | | 6.2 | | | |
| Maximum I²√t for fusing | I ² √t (1) | t = 0.1 ms to 10 ms, no voltage reapplied | | 96.6 | kA²√s | |
| Waxiiidii i ve for fusing | 1-11(1) | $T_J = T_J$ maximum | | 50.0 | KA 13 | |
| Maximum value or threshold voltage | V _{T(TO)} (2) | Low level (3) | $T_J = T_J$ maximum | | 0.82 | V |
| waximum value or threshold voltage | | High level ⁽⁴⁾ | | | 0.86 | |
| Maximum value of on-state slope resistance | r _t (2) | Low level (3) | T _J = T _J maximum | | 3.95 | mΩ |
| Maximum value of on-state slope resistance | 't`' | High level (4) | | | 3.91 | |
| Maximum peak on-state voltage | V _{TM} | / 1 150 A | T _J = 25 °C | | 1.45 | V |
| Maximum peak on-state voltage | | $I_{TM} = 150 \text{ A}$ $T_J = 150 \text{ °C}$ | | 1.41 | V | |
| Maximum non-repetitive rate of rise of turned | dl/dt | $T_J = 25$ °C, from 0.67 V_{DRM} , $I_{TM} = \pi \times I_{T(AV)}$, $I_g = 500$ mA, | | 150 | A/µs | |
| on current | ui/ut | $t_r < 0.5 \ \mu s, \ t_p > 6 \ \mu s$ | | 7/μ3 | | |
| Maximum holding current | I _H | $T_J = 25$ °C, anode supply = 6 V, resistive load, | | 250 | | |
| | •п | gate open circuit | | mA | | |
| Maximum latching current | I∟ | T _J = 25 °C, anode supply = 6 V, resistive load 400 | | | | |

Notes

- (1) I^2t for time $t_x = I^2\sqrt{t} \ x \ \sqrt{t_x}$
- $^{(2)}$ Average power = $V_{T(TO)} \; x \; I_{T(AV)} + r_t \; x \; (I_{T(RMS)})^2$
- (3) 16.7 % $\times \pi \times I_{AV} < I < \pi \times I_{AV}$
- $^{(4)}~I>\pi~x~I_{AV}$

| TRIGGERING | | | | | |
|--|--------------------|---|-----------------------------------|--------|-------|
| PARAMETER | SYMBOL | TEST CO | ONDITIONS | VALUES | UNITS |
| Maximum peak gate power | P _{GM} | | | 12 | w |
| Maximum average gate power | P _{G(AV)} | | | 3 | VV |
| Maximum peak gate current | I _{GM} | | | 3 | Α |
| Maximum peak negative gate voltage | -V _{GM} | | | 10 | |
| Maximum gate voltage required to trigger | | T _J = -40 °C | Anode supply = 6 V resistive load | 4.0 | V |
| | V_{GT} | T _J = 25 °C | | 2.1 | |
| | | T _J = 125 °C | | 1.7 | |
| | | T _J = -40 °C | Anode supply = 6 V resistive load | 270 | |
| Maximum gate current required to trigger | I _{GT} | T _J = 25 °C | | 150 | mA |
| | | T _J = 125 °C | | 80 | |
| Maximum gate voltage that will not trigger | V_{GD} | T _J = 150 °C, 80 % V _{DRM} applied | | 0.2 | V |
| Maximum gate current that will not trigger | I_{GD} | T _J = 150 °C, 80 % V _{DRM} applied 10 | | mA | |

| BLOCKING | | | | |
|---|---------------------------------------|---|--------------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | VALUES | UNITS |
| Maximum peak reverse and off-state leakage current at V _{RRM} , V _{DRM} | I _{RRM,} I _{DRM} | T _J = 125 °C, gate open circuit | 10 | mA |
| Maximum RMS insulation voltage | V _{INS} | 50 Hz | 2500 (1 min) | V |
| Maximum critical rate of rise of off-state voltage | dV/dt | T _J = 150 °C, linear to 0.8 V _{DRM} | 1000 | V/µs |



| THERMAL AND MECHANICAL SPECIFICATIONS | | | | | |
|--|--------------|-------------------|--|-------------|-------|
| PARAMETER | | SYMBOL | SYMBOL TEST CONDITIONS | | UNITS |
| Junction operating temperature | range | TJ | | -40 to +125 | °C |
| Storage temperature range | | T _{Stg} | | -40 10 +125 | C |
| Maximum internal thermal resis junction to case per leg | tance, | R _{thJC} | DC operation | 0.2 | °C/W |
| Typical thermal resistance, case to heat sink per module | | R _{thCS} | Mounting surface flat, smooth, and greased | 0.1 | C/VV |
| Mounting torque ± 10 % | to heat sink | - | A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. | 1.3 | Nm |
| Approximate weight | | | | 30 | g |
| Case style | | | | SOT | -227 |

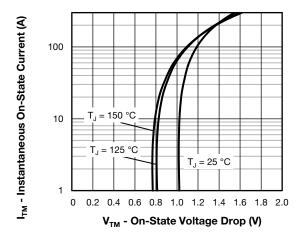


Fig. 1 - I_{TM} vs. V_{TM} (On-State Voltage Drop Characteristics)

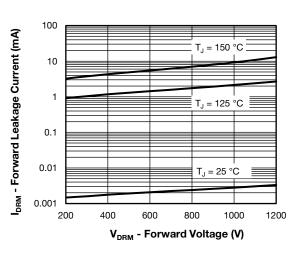


Fig. 2 - I_{DRM} vs. V_{DRM} (Forward Leakage Current)

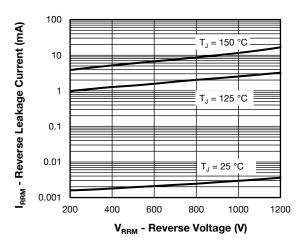


Fig. 3 - I_{RRM} vs. V_{RRM} (Reverse Leakage Current)

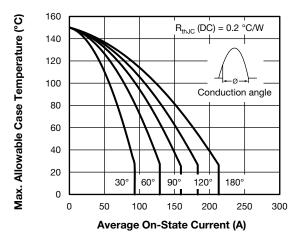


Fig. 4 - Maximum Allowable Case Temperature vs. Average On-State Current (Current Rating Characteristics)



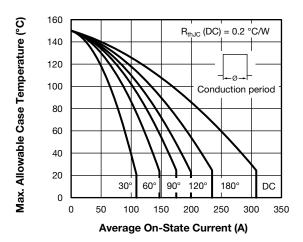


Fig. 5 - Maximum Allowable Case Temperature vs. Average On-State Current (Current Rating Characteristics)

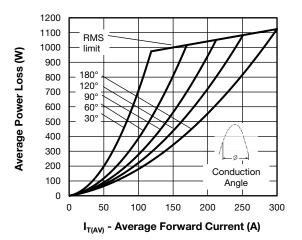
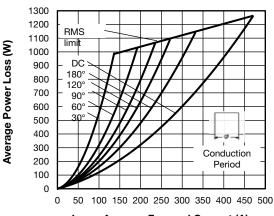
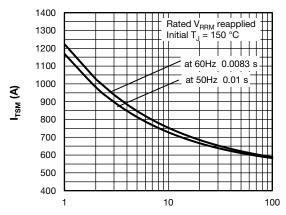


Fig. 6 - Average Power Loss vs. Average Forward Current (Forward Power Loss Characteristics)



 $\mathbf{I}_{\mathrm{T(AV)}}$ - Average Forward Current (A)

Fig. 7 - Average Power Loss vs. Average Forward Current (Forward Power Loss Characteristics)



Number of Equal Amplitude Half Cycle Current Pulses (N)

Fig. 8 - I_{TSM} vs. N (Non-Repetitive peak Forward Surge Current vs. Number Pulses)

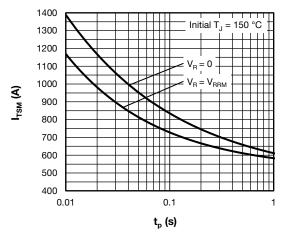


Fig. 9 - I_{TSM} vs. t_p (Non-Repetitive peak Forward Surge Current vs. Pulse Duration)



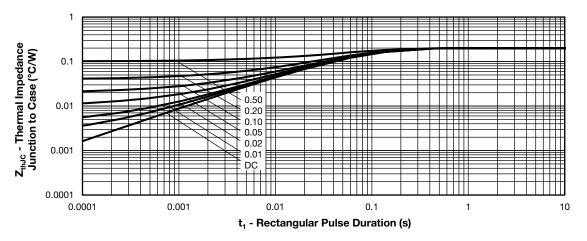
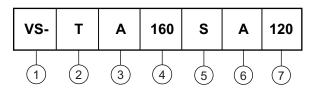


Fig. 10 - Z_{thJC} Thermal Impedance Junction to Case vs. t₁ Rectangular Pulse Duration (Maximum Thermal Impedance Z_{thJC} Characteristics)

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Thyristor dice

Present silicon generation

4 - Rating current

5 - Single thyristor

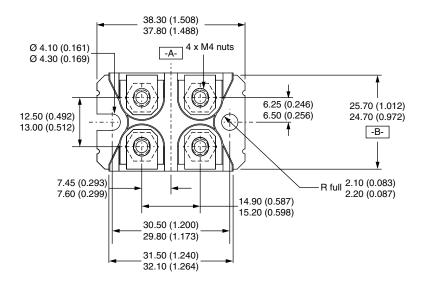
6 - Isolated SOT-227

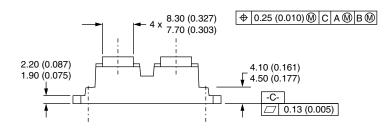
7 - Voltage rating 120 = 1200 V

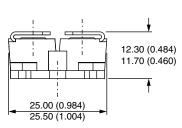
| CIRCUIT DESCRIPTION | CIRCUIT CONFIGURATION CODE | CIRCUIT DRAWING |
|---------------------|----------------------------|--------------------------|
| Single thyristor | S | Lead Assignment 4 1 2 |

| LINKS TO RELATED DOCUMENTS | | | | | |
|----------------------------|--------------------------|--|--|--|--|
| Dimensions | www.vishay.com/doc?95423 | | | | |
| Packaging information | www.vishay.com/doc?95425 | | | | |
| Application note | www.vishay.com/doc?95527 | | | | |

DIMENSIONS in millimeters (inches): **SOT-227 Gen 2**







Note

Controlling dimension: millimeter

SOT-227 Generation 2

DIMENSIONS in millimeters (inches)





Note

· Controlling dimension: millimeter



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